

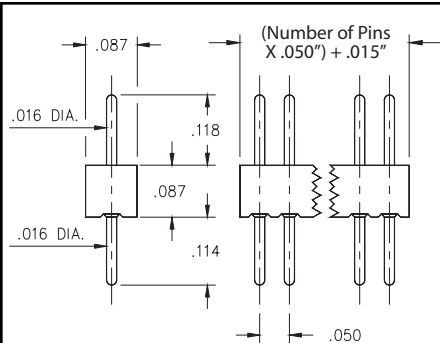


Fig. 1

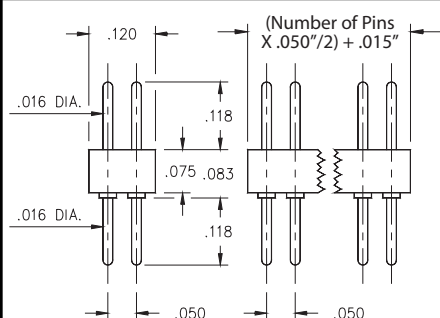


Fig. 2

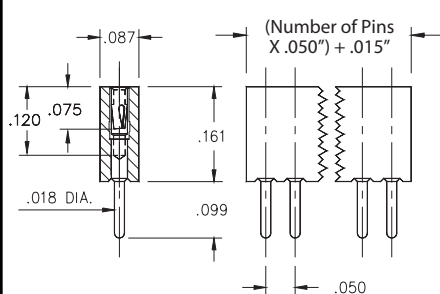


Fig. 3

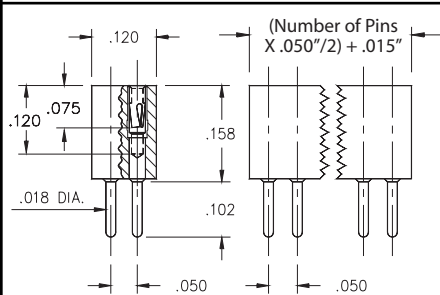


Fig. 4

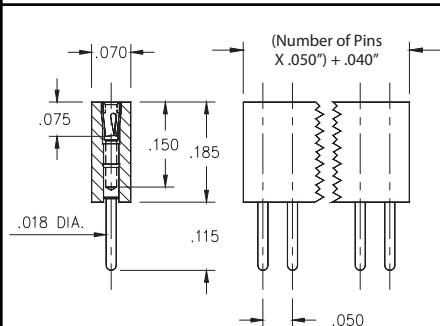
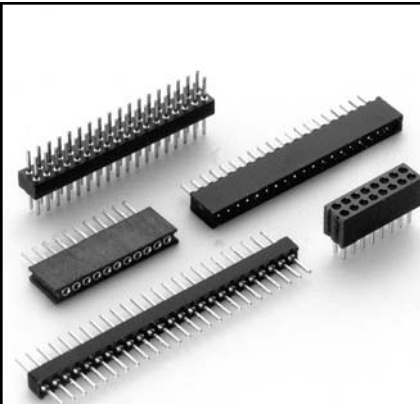


Fig. 5

- Series 850 single and double row interconnects have .050" pin spacing and permit board stacking as low as .248".
- Pin headers have .016" dia. pins. (MM# 4006-0 see page 166 for details).
- MM# 4890-0 and 0467 receptacles use M-M#11 Hi-Rel, 3-finger beryllium copper contacts rated at 3 amps. (#11 contact accepts pin diameters from .015-.020)
- Insulators are high temp. thermo-plastic, suitable for all soldering operations.



Ordering Information

Fig. 1

Single Row .087" Profile Pin Header

850-XX-0_-10-001000

Specify # of pins → 01-50

Fig. 2

Double Row .075" Profile Pin Header

852-XX-_-10-001000

Specify # of pins → 002-100



XX= Plating Code
See Below

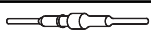
SPECIFY PLATING CODE XX=

10◇

90

40◇

Pin Plating



10μ" Au

200μ" Sn/Pb

200μ" Sn

Fig. 3

Single Row .161" Profile Socket

851-XX-0_-10-001000

Specify # of pins → 01-50

Fig. 4

Double Row .161" Profile Socket

853-XX-_-10-001000

Specify # of pins → 002-100

Fig. 5

Single Row .185" Profile Socket

851-XX-0_-10-002000

Specify # of pins → 01-77



XX= Plating Code
See Below

SPECIFY PLATING CODE XX=

13◇

93

99

43◇

44◇

Sleeve (Pin)



10μ" Au

200μ" Sn/Pb

200μ" Sn/Pb

200μ" Sn

200μ" Sn

Contact (Clip)



30μ" Au

30μ" Au

200μ" Sn/Pb

30μ" Au

200μ" Sn